## Austin Semiconductor, Inc.

### 128K x 8 SRAM

WITH DUAL CHIP ENABLE

### AVAILABLE AS MILITARY **SPECIFICATIONS**

- •SMD 5962-89598
- •MIL-STD-883

#### **FEATURES**

- High Speed: 12, 15, 20, 25, 35, 45, 55 and 70 ns
- Battery Backup: 2V data retention
- Low power standby
- High-performance, low-power CMOS process
- Single +5V (+10%) Power Supply
- Easy memory expansion with CE1\, CE2, and OE\
- All inputs and outputs are TTL compatible

OPTIONS • Timing	MARKIN	IG
12ns access	-12 (co	ntact factory)
15ns access	-15	•
20ns access	-20	
25ns access	-25	
35ns access	-35	
45ns access	-45	
55ns access	-55*	
70ns access	-70*	
• Package(s)•		
Ceramic DIP (400 mil)	C	No. 111
Ceramic DIP (600 mil)	CW	No. 112
Ceramic LCC	EC	No. 207
Ceramic LCC	ECA	No. 208
Ceramic Flatpack	F	No. 303
Ceramic SOJ	DCJ	No. 501

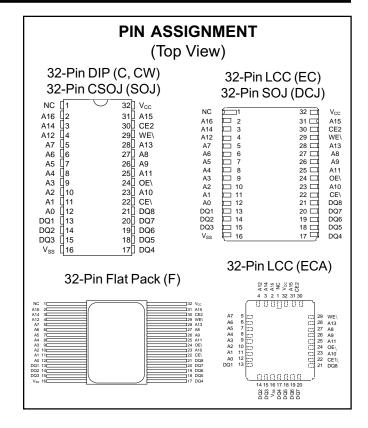
• 2V data retention/low power L

\*Electrical characteristics identical to those provided for the 45ns access devices.

For more products and information please visit our web site at www.austinsemiconductor.com

SOJ

No. 507



### GENERAL DESCRIPTION

The MT5C1008 SRAM employs high-speed, low power CMOS designs using a four-transistor memory cell, and are fabricated using double-layer metal, double-layer polysilicon technology.

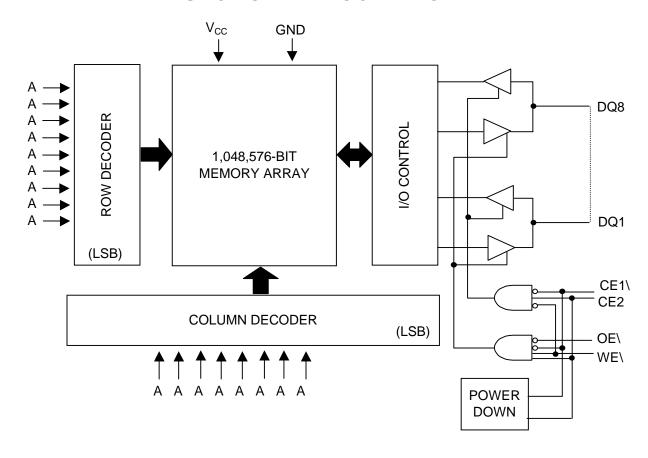
For design flexibility in high-speed memory applications, this device offers dual chip enables (CE1\, CE2) and output enable (OE\). These control pins can place the outputs in High-Z for additional flexibility in system design. All devices operate from a single +5V power supply and all inputs and outputs are fully TTL compatible.

Writing to these devices is accomplished when write enable (WE\) and CE1\ inputs are both LOW and CE2 is HIGH. Reading is accomplished when WE\ and CE2 remain HIGH and CE1\ and OE\ go LOW. The devices offer a reduced power standby mode when disabled, allowing system designs to achieve low standby power requirements.

The "L" version offers a 2V data retention mode, reducing current consumption to 1mA maximum.

Ceramic SOJ

### **FUNCTIONAL BLOCK DIAGRAM**



**NOTE:** The two least significant row address bits (A8 and A6) are encoded using gray code.

### **TRUTH TABLE**

MODE	OE/	CE1\	CE2	WE\	DQ	POWER
STANDBY	Χ	Η	Χ	Χ	HIGH-Z	STANDBY
STANDBY	Χ	Χ	L	Χ	HIGH-Z	STANDBY
READ	L	L	Ι	Ι	Q	ACTIVE
READ	Н	L	Ι	Ι	HIGH-Z	ACTIVE
WRITE	Х	L	Н	L	D	ACTIVE



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#### ABSOLUTE MAXIMUM RATINGS\*

Supply Voltage Range (Vcc)	5V to +6.0V
Storage Temperature	65°C to +150°C
Short Circuit Output Current (per I/O)	20mA
Voltage on any Pin Relative to Vss	5V to Vcc+1 V
Max Junction Temperature**	+150°C
Power Dissipation	1 W

\*Stresses at or greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods will affect reliability. Refer to page 17 of this datasheet for a technical note on this subject.

\*\* Junction temperature depends upon package type, cycle time, loading, ambient temperature and airflow, and humidity.

### ELECTRICAL CHARACTERISTICS AND RECOMMENDED DC OPERATING CONDITIONS

 $(-55^{\circ}\text{C} \le T_{c} \le 125^{\circ}\text{C} \& -45^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}; \ V_{cc} = 5.0\text{V} \pm 10\%)$ 

DESCRIPTION	CONDITIONS	SYM	MIN	MAX	UNITS	NOTES
Input High (Logic 1) Voltage		$V_{IH}$	2.2	V <sub>CC</sub> +0.5	V	1
Input Low (Logic 0) Voltage		V <sub>IL</sub>	-0.5	0.8	V	1, 2
Input Leakage Current	0V≤V <sub>IN</sub> ≤V <sub>CC</sub>	IL <sub>I</sub>	-10	10	μA	
Output Leakage Current	Output(s) disabled 0V≤V <sub>OUT</sub> ≤V <sub>CC</sub>	ILO	-10	10	μΑ	
Output High Voltage	I <sub>OH</sub> =-4.0mA	V <sub>OH</sub>	2.4		V	1
Output Low Voltage	I <sub>OL</sub> =8.0mA	V <sub>OL</sub>		0.4	V	1

			MAX							
PARAMETER	CONDITIONS	SYM	-12	-15	-20	-25	-35	-45	UNITS	NOTES
Power Supply	$CE \setminus \leq V_{IL}$ ; $OE \setminus WE \setminus ADD CE2 \geq V_{IH}$ $V_{CC} = MAX, f = MAX = 1/t_{RC} (MIN)$		250	180	150	140	135	125	mA	3
Current: Operating	Output Open *L version only	I <sub>CCLP</sub> *	250	180	140	130	125	115	mA	
Power Supply Current: Standby	$CE = V_{IH}$ , $CE2 = V_{IL}$ ; Other Inputs at $\leq V_{IL}$ , $\geq V_{IH}$ , $V_{CC} = MAX$ $f = 0 Hz$	I <sub>SBT</sub>	25	25	25	25	25	25	mA	
	$CE \ge V_{CC} - 0.2V; V_{CC} = MAX$ $V_{IL} \le V_{SS} - 0.2V$ $V_{IH} \ge V_{CC} - 0.2V; F = 0 Hz$	I <sub>SBC</sub>	10	10	10	10	10	10	mA	

### **CAPACITANCE**

DESCRIPTION	CONDITIONS	SYM	MAX	UNITS	NOTES
Input Capacitance (A0-A16)	T 0500 t 4MI-	$C_{I}$	12	pF	4
Output Capacitance	$T_A = 25^{\circ}C$ , $f = 1MHz$ $V_{CC} = 5V$	Co	14	pF	4
Input Capacitance (CE WE OE\)	v <sub>CC</sub> = 3 v	C <sub>I</sub>	20	pF	4

### **ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS**

(Note 5) (-55°C  $\leq$  T<sub>c</sub>  $\leq$  125°C & -40°C to +85°C; V<sub>cc</sub> = 5.0V  $\pm$ 10%)

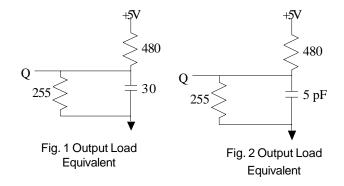
DESCRIPTION		-1	12	-1	15	-2	20	-2	25	-3	35	-4	15		
DESCRIPTION	SYMBOL	MIN	MAX	UNITS	<b>NOTES</b>										
READ CYCLE															
READ cycle time	$t_{RC}$	12		15		20		25		35		45		ns	
Address access time	t <sub>AA</sub>		12		15		20		25		35		45	ns	
Chip Enable access time	t <sub>ACE</sub>		12		15		20		25		35		45	ns	
Output hold from address change	t <sub>OH</sub>	3		3		3		3		3		3		ns	
Chip Enable to output in Low-Z	t <sub>LZCE</sub>	3		3		3		3		3		3		ns	4, 6, 7
Chip disable to output in High-Z	t <sub>HZCE</sub>		7		7		8		10		15		20	ns	4, 6, 7
Output Enable access time	t <sub>AOE</sub>		7		7		7		10		15		20	ns	4, 6, 7
Output Enable to output in Low-Z	t <sub>LZOE</sub>	0		0		0		0		0		0		ns	
Output disable to output in High-Z	t <sub>HZOE</sub>		7		7		8		10		15		20	ns	4, 6, 7
WRITE CYCLE															
WRITE cycle time	t <sub>wc</sub>	12		15		20		25		35		45		ns	
Chip Enable to end of write	t <sub>CW</sub>	11		12		15		20		25		35		ns	
Address valid to end of write	t <sub>AW</sub>	11		12		15		20		25		35		ns	
Address setup time	t <sub>AS</sub>	0		0		0		0		0		0		ns	
Address hold from end of write	t <sub>AH</sub>	0		0		0		0		0		5		ns	
WRITE pulse width	t <sub>WP</sub>	11		12		15		20		25		35		ns	
Data setup time	t <sub>DS</sub>	8		8		10		15		20		20		ns	
Data hold time	t <sub>DH</sub>	0		0		0		0		0		0		ns	
Write disable to output in Low-Z	t <sub>LZWE</sub>	5		5		5		5		5		5		ns	4, 6, 7
Write Enable to output in High-Z	t <sub>HZWE</sub>		7		7		9		10		15		20	ns	4, 6, 7



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#### **ACTEST CONDITIONS**

Input pulse levelsVs:	s to 3.0V
Input rise and fall times	5ns
Input timing reference levels	1.5V
Output reference levels	1.5V
Output load See Figures	1 and 2



### **NOTES**

- 1. All voltages referenced to  $V_{ss}$  (GND).
- 2. -2V for pulse width < 20ns
- 3. I<sub>CC</sub> is dependent on output loading and cycle rates. The specified value applies with the outputs unloaded, and f = 1 Hz.

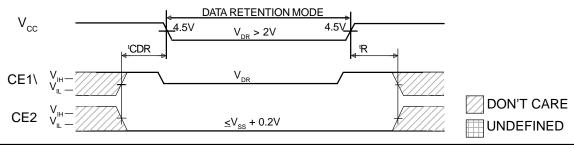
  <sup>1</sup>RC (MIN)
- 4. This parameter is guaranteed but not tested.
- 5. Test conditions as specified with the output loading as shown in Fig. 1 unless otherwise noted.
- 6. 'LZCE, 'LZWE, 'LZOE, 'HZCE, 'HZOE and 'HZWE are specified with CL = 5pF as in Fig. 2. Transition is measured ±200mV typical from steady state voltage, allowing for actual tester RC time constant.

- 7. At any given temperature and voltage condition, 'HZCE is less than 'LZCE, and 'HZWE is less than 'LZWE and 'HZOE is less than 'LZOE.
- 8. WE\is HIGH for READ cycle.
- 9. Device is continuously selected. Chip enables and output enables are held in their active state.
- 10. Address valid prior to, or coincident with, latest occurring chip enable.
- 11. 'RC = Read Cycle Time.
- 12. CE2 timing is the same as CE1\timing. The waveform is inverted.
- 13. Chip enable (CE1\, CE2) and write enable (WE\) can initiate and terminate a WRITE cycle.

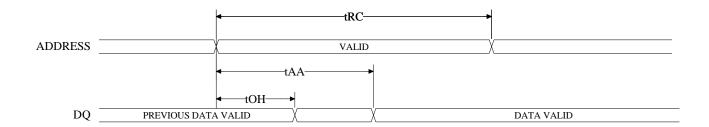
### **DATA RETENTION ELECTRICAL CHARACTERISTICS (L Version Only)**

DESCRIPTION	CONDITIONS	SYMBOL	MIN	MAX	UNITS	NOTES	
V <sub>CC</sub> for Retention Data			$V_{DR}$	2		V	
Data Retention Current	$CE \ge (V_{CC} - 0.2V)$ $V_{IN} \ge (V_{CC} - 0.2V)$ or \le 0.2V, f=0	V <sub>CC</sub> = 2V	I <sub>CCDR</sub>		1.0	mA	
Chip Deselect to Data Retention Time			t <sub>CDR</sub>	0		ns	4
Operation Recovery Time			t <sub>R</sub>	t <sub>RC</sub>		ns	4, 11

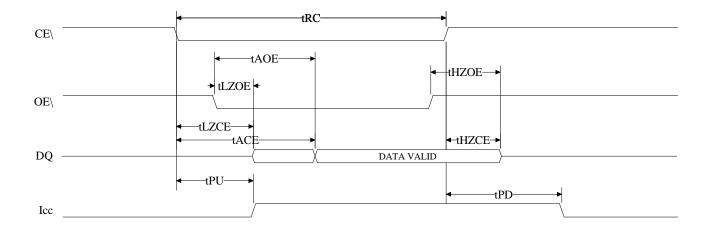
#### LOW Vcc DATA RETENTION WAVEFORM



### READ CYCLE NO. 1 8,9



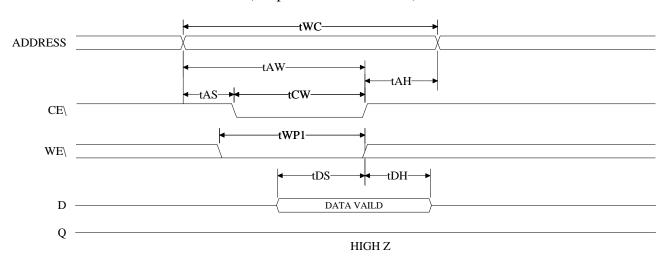
### READ CYCLE NO. $2^{7,8,10,12}$



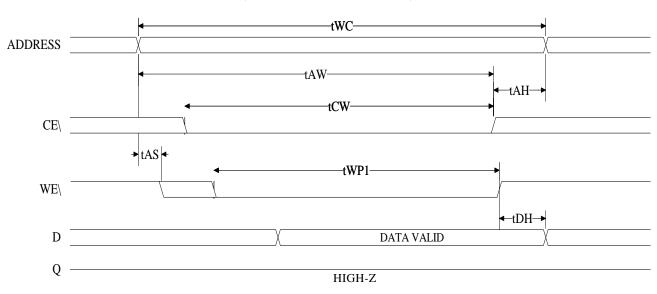


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# WRITE CYCLE NO. 1 12, 13 (Chip Enabled Controlled)



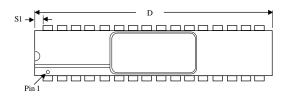
# WRITE CYCLE NO. 2 7, 12, 13 (Write Enabled Controlled)

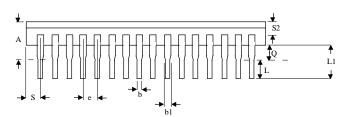


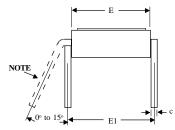
NOTE: Output enable (OE\) is inactive (HIGH).



# ASI Case #111 (Package Designator C) SMD 5962-89598, Case Outline Z

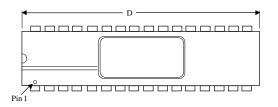


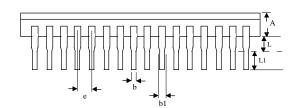


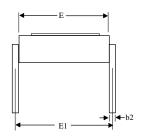


	SMD SPECIFICATIONS							
SYMBOL	MIN	MAX						
А		0.232						
b	0.014	0.023						
b1	0.038	0.065						
С	0.008	0.015						
D		1.700						
E	0.350	0.405						
E1	0.390	0.420						
е	0.100	) BSC						
L	0.125	0.200						
L1	0.150							
Q	0.015	0.060						
S		0.100						
S1	0.005							
S2	0.005							
NOTE:	Either configuration in de	Either configuration in detail A is allowed on SMD.						

# ASI Case #112 (Package Designator CW) SMD 5962-89598, Case Outline X



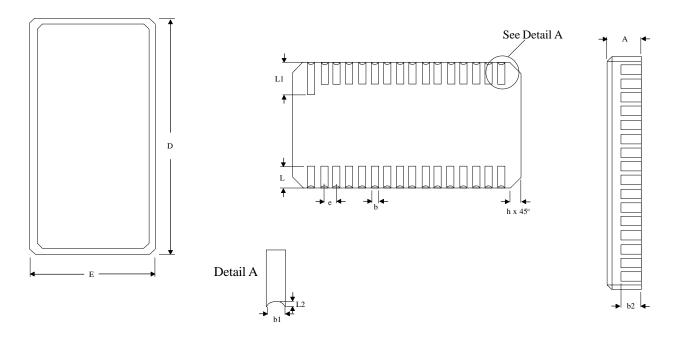




	SMD SPECIFICATIONS					
SYMBOL	MIN	MAX				
Α	0.089	0.111				
b	0.016	0.020				
b1	0.045	0.055				
b2	0.009	0.011				
D	1.585	1.615				
E	0.585	0.605				
E1	0.595	0.610				
е	0.090	0.110				
L	0.040	0.060				
L1	0.125	0.175				

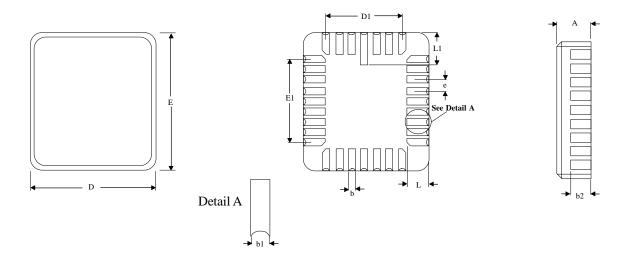


### ASI Case #207 (Package Designator EC) SMD 5962-89598, Case Outline U



	SMD SPECIFICATIONS						
SYMBOL	MIN	MAX					
Α	0.080	0.100					
b	0.022	0.028					
b1	0.006	0.022					
b2	0.040						
D	0.800	0.840					
E	0.392	0.408					
е	0.050	) BSC					
h	0.012	2 REF					
L	0.070	0.080					
L1	0.090	0.110					
L2	0.003 0.015						

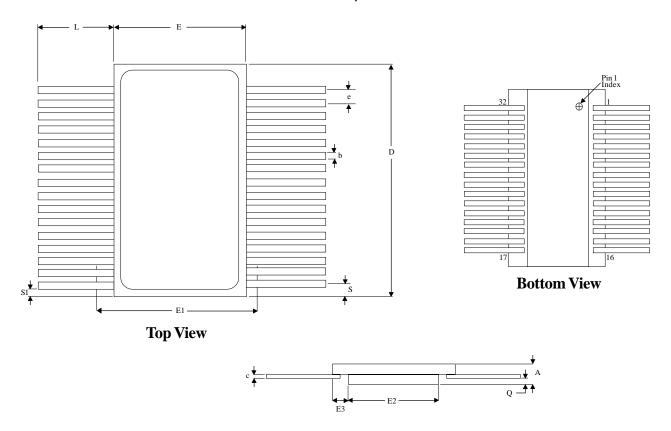
### ASI Case #208 (Package Designator ECA) SMD 5962-89598, Case Outline M



	SMD SPECIFICATIONS		
SYMBOL	MIN	MAX	
А	0.060	0.120	
b	0.022	0.028	
b1	0.004	0.014	
b2	0.040		
D	0.442	0.458	
D1	0.300	) BSC	
E	0.540	0.560	
E1	0.400 BSC		
е	0.050 BSC		
L	0.045	0.055	
L1	0.075	0.095	

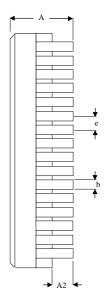


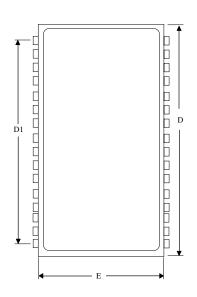
ASI Case #303 (Package Designator F) SMD 5962-89598, Case Outline T

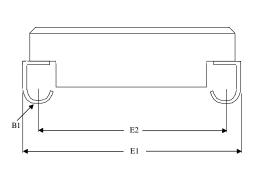


	SMD SPECIFICATIONS		
SYMBOL	MIN	MAX	
Α	0.097	0.125	
b	0.015	0.019	
С	0.003	0.009	
D		0.830	
E	0.400	0.420	
E1		0.450	
E2	0.180		
E3	0.030		
е	0.050	BSC	
L	0.250	0.370	
Q	0.026	0.045	
S		0.045	
S1	0.000		

### ASI Case #501 (Package Designator DCJ) SMD 5962-89598, Case Outline 7

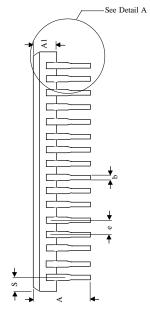


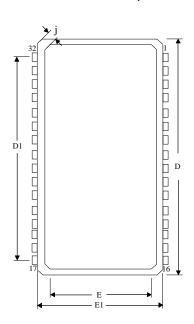


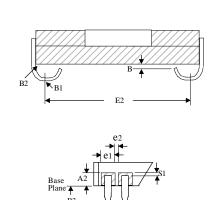


	SMD SPECIFICATIONS		
SYMBOL	MIN	MAX	
А	0.132	0.144	
A2	0.026	0.036	
B1	0.030	0.040	
b	0.015	0.019	
D	0.812	0.828	
D1	0.740	0.760	
E	0.405	0.415	
E1	0.435	0.445	
E2	0.360	0.380	
е	0.050 BSC		

### ASI Case #507 (Package Designator SOJ) SMD 5962-89598, Case Outline Y







Detail A

	SMD SPECIFICATIONS			
SYMBOL	MIN	MAX		
Α	0.120	0.165		
A1	0.088	0.120		
A2	0.070	) REF		
В	0.010	) REF		
B1	0.030	R TYP		
B2	0.020	) REF		
B3	0.025	0.045		
b	0.015	0.019		
D	0.816	0.838		
D1	0.750	REF		
E	0.419	0.431		
E1	0.430	0.445		
E2	0.360	0.380		
е	0.050	0.050 BSC		
e1	0.038	0.038 TYP		
e2	0.005			
j	0.005 TYP			
S	0.030	0.040		
S1	0.020	) TYP		

<sup>\*</sup>All measurements are in inches.

### ORDERING INFORMATION

**EXAMPLE:** MT5C1008CW-45/883C

EXAMPLE: 1011301008000-45/8830				
Device	Package	Speed	Options**	Process
Number	Type	ns	Options	FIOCESS
MT5C1008	С	-12	L	/*
MT5C1008	CW	-12	L	/*
MT5C1008	С	-15	L	/*
MT5C1008	CW	-15	L	/*
MT5C1008	С	-20	L	/*
MT5C1008	CW	-20	L	/*
MT5C1008	С	-25	L	/*
MT5C1008	CW	-25	L	/*
MT5C1008	С	-35	L	/*
MT5C1008	CW	-35	L	/*
MT5C1008	С	-45	L	/*
MT5C1008	CW	-45	L	/*
MT5C1008	С	-55	L	/*
MT5C1008	CW	-55	L	/*
MT5C1008	С	-70	Ĺ	/*
MT5C1008	CW	-70	L	/*
·			·	

EXAMPLE: MT5C1008ECA-25L/XT

Device	Package	Speed	Options**	Process
Number	Type	ns	Options	FIOCESS
MT5C1008	EC	-12	L	/*
MT5C1008	ECA	-12	L	/*
MT5C1008	EC	-15	L	/*
MT5C1008	ECA	-15	L	/*
MT5C1008	EC	-20	L	/*
MT5C1008	ECA	-20	L	/*
MT5C1008	EC	-25	L	/*
MT5C1008	ECA	-25	L	/*
MT5C1008	EC	-35	L	/*
MT5C1008	ECA	-35	L	/*
MT5C1008	EC	-45	L	/*
MT5C1008	ECA	-45	L	/*
MT5C1008	EC	-55	L	/*
MT5C1008	ECA	-55	L	/*
MT5C1008	EC	-70	L	/*
MT5C1008	ECA	-70	L	/*

**EXAMPLE:** MT5C1008F-25L/883C

Device Number	Package Type	Speed ns	Options**	Process
MT5C1008	F	-12	L	/*
MT5C1008	F	-15	L	/*
MT5C1008	F	-20	L	/*
MT5C1008	F	-25	L	/*
MT5C1008	F	-35	L	/*
MT5C1008	F	-45	L	/*
MT5C1008	F	-55	L	/*
MT5C1008	F	-70	L	/*

EXAMPLE: MT5C1008DCJ-35/IT

Device	Package	Speed	Ontions** Proces	
Number	Type	ns	Options**	Process
MT5C1008	DCJ	-12	L	/*
MT5C1008	SOJ	-12	L	/*
MT5C1008	DCJ	-15	L	/*
MT5C1008	SOJ	-15	L	/*
MT5C1008	DCJ	-20	L	/*
MT5C1008	SOJ	-20	L	/*
MT5C1008	DCJ	-25	L	/*
MT5C1008	SOJ	-25	L	/*
MT5C1008	DCJ	-35	L	/*
MT5C1008	SOJ	-35	L	/*
MT5C1008	DCJ	-45	L	/*
MT5C1008	SOJ	-45	L	/*
MT5C1008	DCJ	-55	L	/*
MT5C1008	SOJ	-55	L	/*
MT5C1008	DCJ	-70	Ĺ	/*
MT5C1008	SOJ	-70	L	/*

### \*AVAILABLE PROCESSES

### \*\* OPTIONS

L = 2V Data Retention/Low Power



## **ASI TO DSCC PART NUMBER CROSS REFERENCE**

### ASI Package Designator C & CW ASI Package Designator EC & ECA

ASI Part #	SMD Part #	ASI Part #	SMD Part #
MT5C1008C-20/883C	5962-8959838MZA	MT5C1008EC-20/883C	5962-8959838MUA
MT5C1008C-20L/883C	5962-8959821MZA	MT5C1008EC-20L/883C	5962-8959821MUA
MT5C1008C-25/883C	5962-8959837MZA	MT5C1008EC-25/883C	5962-8959837MUA
MT5C1008C-25L/883C	5962-8959820MZA	MT5C1008EC-25L/883C	5962-8959820MUA
MT5C1008C-35/883C	5962-8959836MZA	MT5C1008EC-35/883C	5962-8959836MUA
MT5C1008C-35L/883C	5962-8959819MZA	MT5C1008EC-35L/883C	5962-8959819MUA
MT5C1008C-45/883C	5962-8959835MZA	MT5C1008EC-45/883C	5962-8959835MUA
MT5C1008C-45L/883C	5962-8959818MZA	MT5C1008EC-45L/883C	5962-8959818MUA
MT5C1008C-55/883C	5962-8959834MZA	MT5C1008EC-55/883C	5962-8959834MUA
MT5C1008C-55L/883C	5962-8959817MZA	MT5C1008EC-55L/883C	5962-8959817MUA
MT5C1008C-70/883C	5962-8959833MZA	MT5C1008EC-70/883C	5962-8959833MUA
MT5C1008C-70L/883C	5962-8959816MZA	MT5C1008EC-70L/883C	5962-8959816MUA
MT5C1008CW-20/883C	5962-8959838MXA	MT5C1008ECA-20/883C	5962-8959838MMA
MT5C1008CW-20L/883C	5962-8959821MXA	MT5C1008ECA-20L/883C	5962-8959821MMA
MT5C1008CW-25/883C	5962-8959837MXA	MT5C1008ECA-25/883C	5962-8959837MMA
MT5C1008CW-25L/883C	5962-8959820MXA	MT5C1008ECA-25L/883C	5962-8959820MMA
MT5C1008CW-35/883C	5962-8959836MXA	MT5C1008ECA-35/883C	5962-8959836MMA
MT5C1008CW-35L/883C	5962-8959819MXA	MT5C1008ECA-35L/883C	5962-8959819MMA
MT5C1008CW-45/883C	5962-8959835MXA	MT5C1008ECA-45/883C	5962-8959835MMA
MT5C1008CW-45L/883C	5962-8959818MXA	MT5C1008ECA-45L/883C	5962-8959818MMA
MT5C1008CW-55/883C	5962-8959834MXA	MT5C1008ECA-55/883C	5962-8959834MMA
MT5C1008CW-55L/883C	5962-8959817MXA	MT5C1008ECA-55L/883C	5962-8959817MMA
MT5C1008CW-70/883C	5962-8959833MXA	MT5C1008ECA-70/883C	5962-8959833MMA
MT5C1008CW-70L/883C	5962-8959816MXA	MT5C1008ECA-70L/883C	5962-8959816MMA

### **ASI Package Designator F**

### ASI Package Designator DCJ & SOJ

ASI Part #	SMD Part #	ASI Part #	SMD Part #
MT5C1008F-20/883C	5962-8959838MTA	MT5C1008DCJ-20/883C	5962-8959838M7A
MT5C1008F-20L/883C	5962-8959821MTA	MT5C1008DCJ-20L/883C	5962-8959821M7A
MT5C1008F-25/883C	5962-8959837MTA	MT5C1008DCJ-25/883C	5962-8959837M7A
MT5C1008F-25L/883C	5962-8959820MTA	MT5C1008DCJ-25L/883C	5962-8959820M7A
MT5C1008F-35/883C	5962-8959836MTA	MT5C1008DCJ-35/883C	5962-8959836M7A
MT5C1008F-35L/883C	5962-8959819MTA	MT5C1008DCJ-35L/883C	5962-8959819M7A
MT5C1008F-45/883C	5962-8959835MTA	MT5C1008DCJ-45/883C	5962-8959835M7A
MT5C1008F-45L/883C	5962-8959818MTA	MT5C1008DCJ-45L/883C	5962-8959818M7A
MT5C1008F-55/883C	5962-8959834MTA	MT5C1008DCJ-55/883C	5962-8959834M7A
MT5C1008F-55L/883C	5962-8959817MTA	MT5C1008DCJ-55L/883C	5962-8959817M7A
MT5C1008F-70/883C	5962-8959833MTA	MT5C1008DCJ-70/883C	5962-8959833M7A
MT5C1008F-70L/883C	5962-8959816MTA	MT5C1008DCJ-70L/883C	5962-8959816M7A
		MT5C1008SOJ-20/883C	5962-8959838MYA
		MT5C1008SOJ-20L/883C	5962-8959821MYA
		MT5C1008SOJ-25/883C	5962-8959837MYA
		MT5C1008SOJ-25L/883C	5962-8959820MYA
		MT5C1008SOJ-35/883C	5962-8959836MYA
		MT5C1008SOJ-35L/883C	5962-8959819MYA
		MT5C1008SOJ-45/883C	5962-8959835MYA
		MT5C1008SOJ-45L/883C	5962-8959818MYA
		MT5C1008SOJ-55/883C	5962-8959834MYA
		MT5C1008SOJ-55L/883C	5962-8959817MYA
* ASI part number is for reference	only. Orders received referencing	MT5C1008SOJ-70/883C	5962-8959833MYA
the SMD part number will be proce	essed per the SMD.	MT5C1008SOJ-70L/883C	5962-8959816MYA
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**DATE: 2/6/01** 

# **Technical Note:**

# 128Kx8 SRAM – Maximum Recommended Supply Voltage and Ambient Temperature

### **Compliance:**

This product fully meets and is tested in compliance with SMD# 5962-89598 and tested in accordance with JESD78.

### **Specific Product Affected:**

Die Manufacturer: Alliance Semiconductor Corporation

Die Name: AS2008SA

Device Types: MT5C1008, MT5C1009

Speed Grades: All

Package Designators: All

Identifying Date Code Marking: Change implemented on product starting with date code 0100.

### **Characteristic Identified:**

Austin Semiconductor, Inc. has received notification from this die vendor, Alliance Semiconductor Corp., that operation at high Vcc's of 6 volts and beyond may result in a latch-up condition. This can cause permanent damage to the device.

### **Recommendation:**

During use in system applications and during manufacturing processes, including Burn-In and Test, the devices should not be subjected to Vcc Supply Voltages higher than 5.5Volts at 125°C.